



Title: LINEAR CHEMICAL MECHANICAL PLANARIZATION (CMP) SYSTEM AND METHOD FOR
PLANARIZING A WAFER IN A SINGLE CMP MODULE

Application No.: 10/743,923

Docket No. LAM2P452

Inventor: KIERMASZ

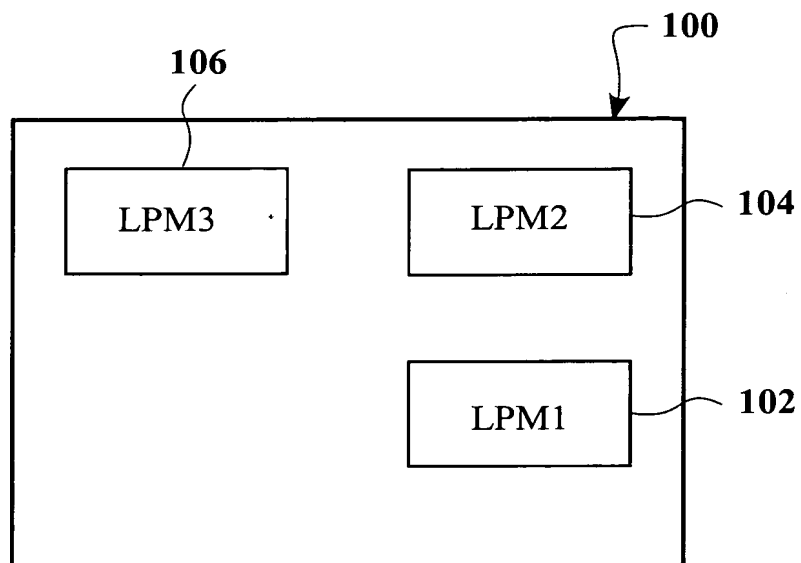


FIG. 1
(Prior Art)

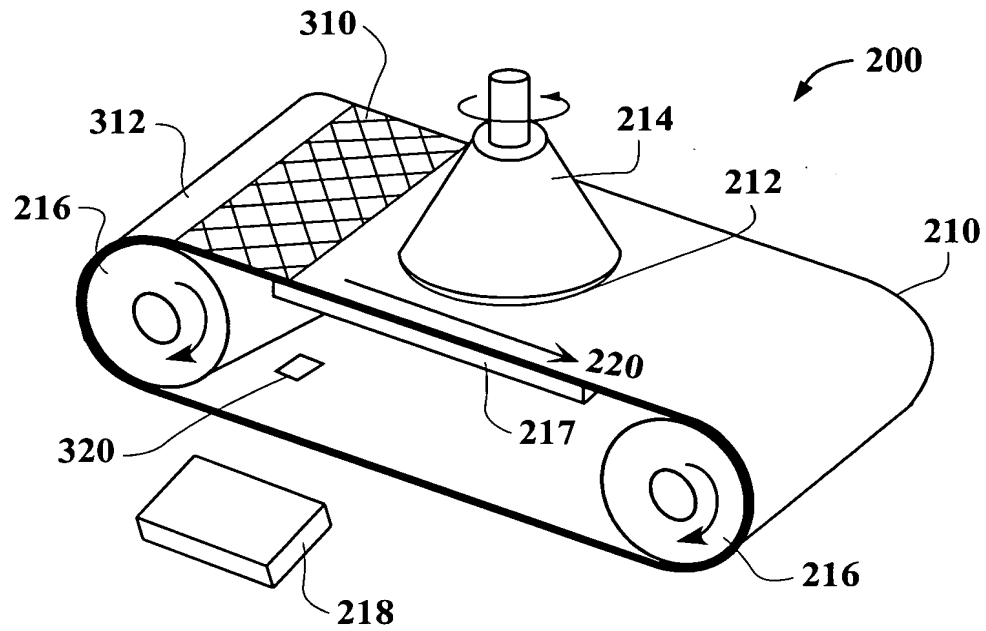


FIG. 2A

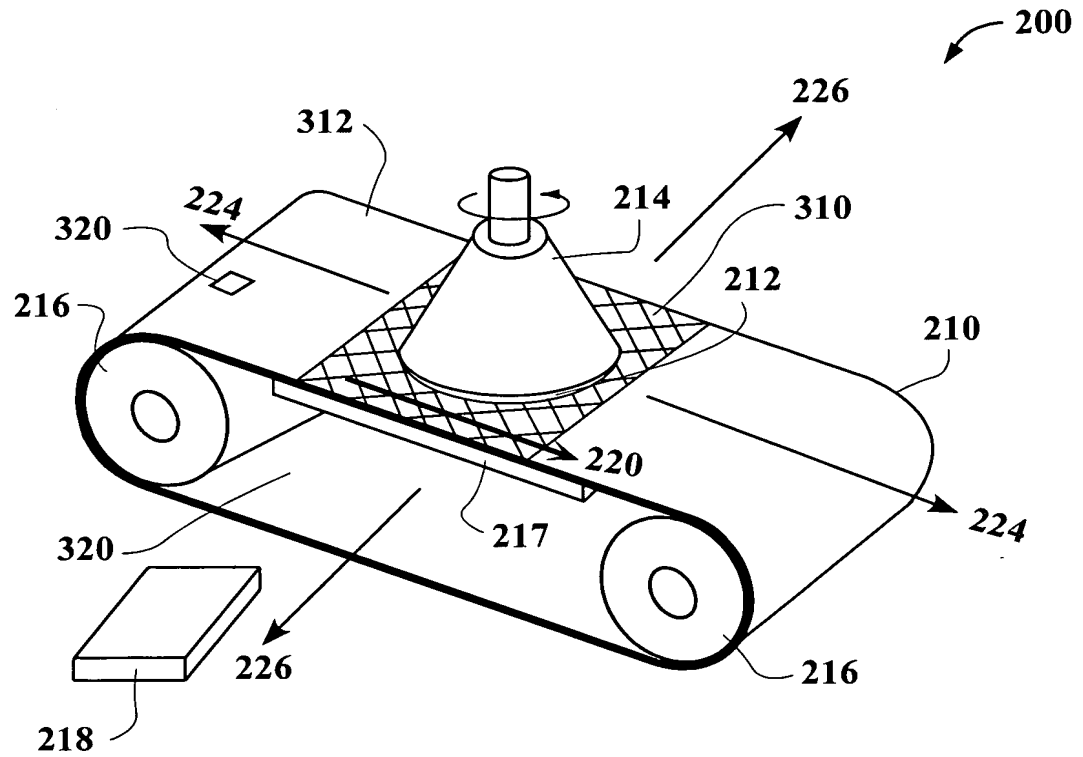


FIG. 2B

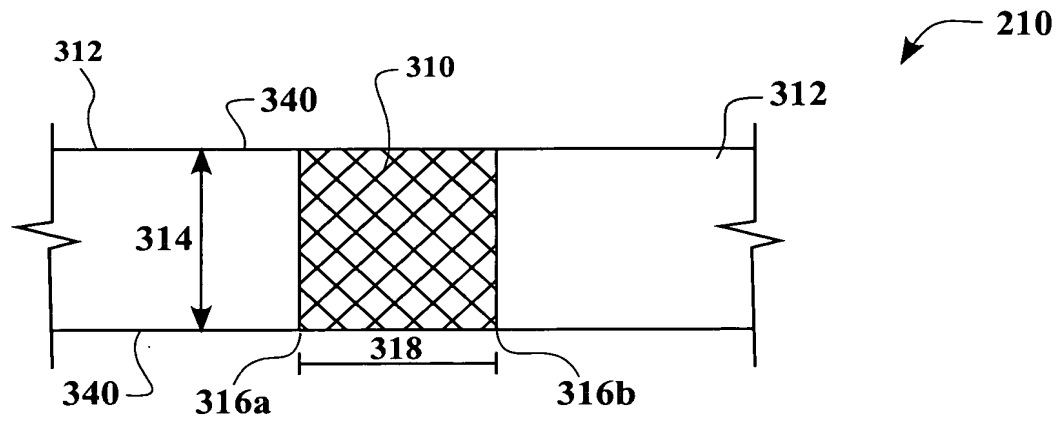


FIG. 3A

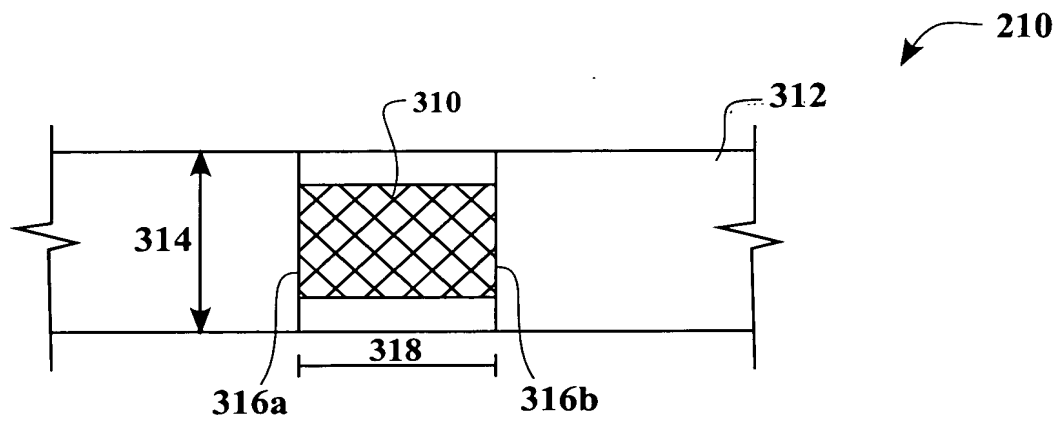


FIG. 3B

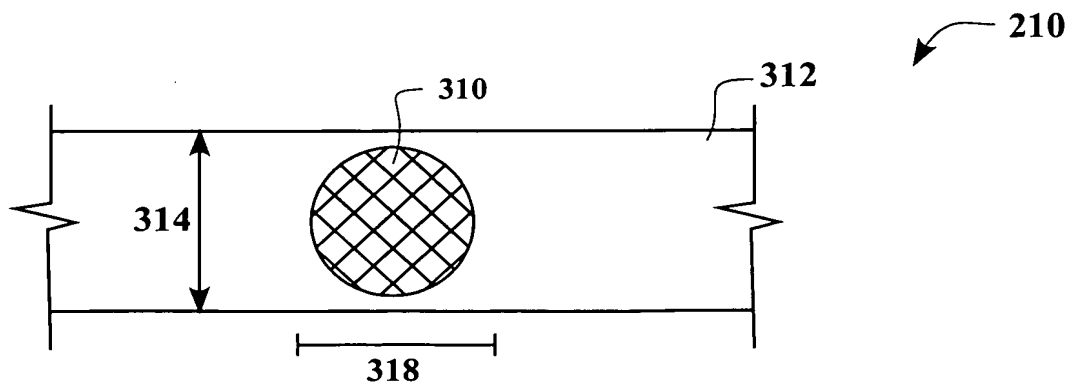


FIG. 3C